

Electronic Patent Application Fee Transmittal

Application Number:	10719020
Filing Date:	24-Nov-2003
Title of Invention:	Method for preparing a circuit board material having a conductive base and a resistance layer
First Named Inventor/Applicant Name:	Akira Matsuda
Filer:	Shuji Yoshizaki/Maya Takakura
Attorney Docket Number:	032130

Filed as Large Entity

Utility under 35 USC 111(a) Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Basic Filing:

Pages:

Claims:

Miscellaneous-Filing:

Petition:

Patent-Appeals-and-Interference:

Post-Allowance-and-Post-Issuance:

Extension-of-Time:

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Request for continued examination	1801	1	810	810
Total in USD (\$)				810